

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		

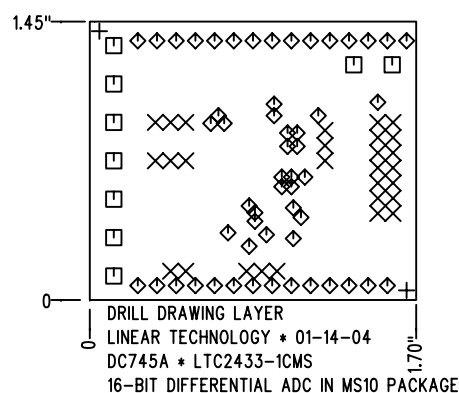
SIZE	QTY	SYM	PLTD
0.07	2	+	NPLTD
0.035	28	X	PLTD
0.064	9	□	PLTD
0.015	54	◇	PLTD

NOTES : Unless Otherwise Specified


1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. SCORING:



7. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.



SHOWN FROM COMPONENT SIDE

APPROVALS			 <div> 1630 MCCATHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY </div>	
	INIT	DATE		
DRAWN			TITLE: FABRICATION DRAWING 16-BIT DIFFERENTIAL ADC IN MS10 PACKAGE	
CHECK				
DESIGN	KIM T.	01-14-04		
ENGR	MART T.	01-14-04		
			SIZE A	REV. A
			DEMO DC745A * LTC2433-1CMS	
SCALE = NONE			DES- 0000	SHT 1 of 1